

QORVO

SiC JFET Division

Is Now Part of

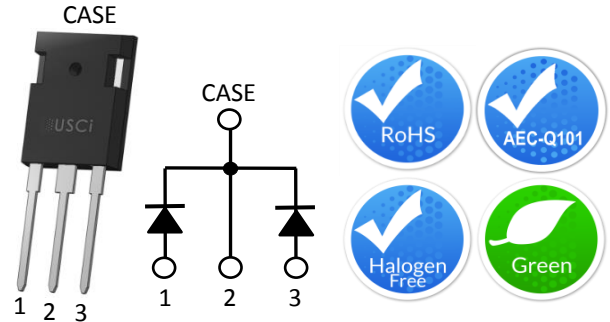
onsemi™

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Description

United Silicon Carbide, Inc. offers the 3rd generation of high performance SiC Merged-PiN-Schottky (MPS) diodes. With zero reverse recovery charge and 175°C maximum junction temperature, these diodes are ideally suited for high frequency and high efficiency power systems with minimum cooling requirements.



Features

- ◆ 175°C maximum operating junction temperature
- ◆ Easy paralleling
- ◆ Extremely fast switching not dependent on temperature
- ◆ No reverse or forward recovery
- ◆ Enhanced surge current capability, MPS structure
- ◆ Excellent thermal performance, Ag sintered
- ◆ 100% UIS tested
- ◆ AEC-Q101 qualified
- ◆ AECQ Qualified

Part Number	Package	Marking
UJ3D06520KSD	TO-247-3L	UJ3D06520KSD

Typical Applications

- ◆ Power converters
- ◆ Industrial motor drives
- ◆ Switching-mode power supplies
- ◆ Power factor correction modules

Maximum Ratings

Parameter	Symbol	Test Conditions	Value (Leg/Device)	Units
DC blocking voltage	V_R		650	V
Repetitive peak reverse voltage, $T_j=25^\circ\text{C}$	V_{RRM}		650	V
Surge peak reverse voltage	V_{RSM}		650	V
Maximum DC forward current	I_F	$T_C = 152^\circ\text{C}$	10/20	A
Non-repetitive forward surge current sine halfwave	I_{FSM}	$T_C = 25^\circ\text{C}, t_p = 10\text{ms}$	70/140	A
		$T_C = 110^\circ\text{C}, t_p = 10\text{ms}$	60/120	
Repetitive forward surge current sine halfwave, $D=0.1$	I_{FRM}	$T_C = 25^\circ\text{C}, t_p = 10\text{ms}$	45.9/91.8	A
		$T_C = 110^\circ\text{C}, t_p = 10\text{ms}$	28.7/57.4	
Non-repetitive peak forward current	$I_{F,max}$	$T_C = 25^\circ\text{C}, t_p = 10\mu\text{s}$	455/910	A
		$T_C = 110^\circ\text{C}, t_p = 10\mu\text{s}$	455/910	
i^2t value	$\int i^2 dt$	$T_C = 25^\circ\text{C}, t_p = 10\text{ms}$	24.5/98	A^2s
		$T_C = 110^\circ\text{C}, t_p = 10\text{ms}$	18/72	
Power dissipation	P_{Tot}	$T_C = 25^\circ\text{C}$	136.4/272.8	W
		$T_C = 152^\circ\text{C}$	20.9/41.8	
Maximum junction temperature	$T_{J,max}$		175	$^\circ\text{C}$
Operating and storage temperature	T_J, T_{STG}		-55 to 175	$^\circ\text{C}$
Soldering temperatures, wavesoldering only allowed at leads	T_{sold}	1.6mm from case for 10s	260	$^\circ\text{C}$

Electrical Characteristics

$T_J = +25^\circ\text{C}$ unless otherwise specified

Parameter	Symbol	Test Conditions	Value (Leg/Device)			Units
			Min	Typ	Max	
Forward voltage	V_F	$I_F = 10/20\text{A}, T_J = 25^\circ\text{C}$	-	1.5	1.7	V
		$I_F = 10/20\text{A}, T_J = 150^\circ\text{C}$	-	1.68	2	
		$I_F = 10/20\text{A}, T_J = 175^\circ\text{C}$	-	1.75	2.1	
Reverse current	I_R	$V_R = 650\text{V}, T_J = 25^\circ\text{C}$	-	10/20	60/120	μA
		$V_R = 650\text{V}, T_J = 175^\circ\text{C}$	-	150/300		
Total capacitive charge ⁽¹⁾	Q_C	$V_R = 400\text{V}$		23/46		nC
Total capacitance	C	$V_R = 1\text{V}, f = 1\text{MHz}$		327/654		pF
		$V_R = 300\text{V}, f = 1\text{MHz}$		38/76		
		$V_R = 600\text{V}, f = 1\text{MHz}$		34/68		
Capacitance stored energy	E_C	$V_R = 400\text{V}$		3.4/6.8		μJ

(1) Q_C is independent on T_J , di_F/dt , and I_F as shown in the application note USCi_AN0011.

Thermal characteristics

Parameter	symbol	Test Conditions	Value (Leg/Device)			Units
			Min	Typ	Max	
Thermal resistance	$R_{\theta JC}$			0.82/0.41	1.1/0.55	$^\circ\text{C/W}$

Typical Performance

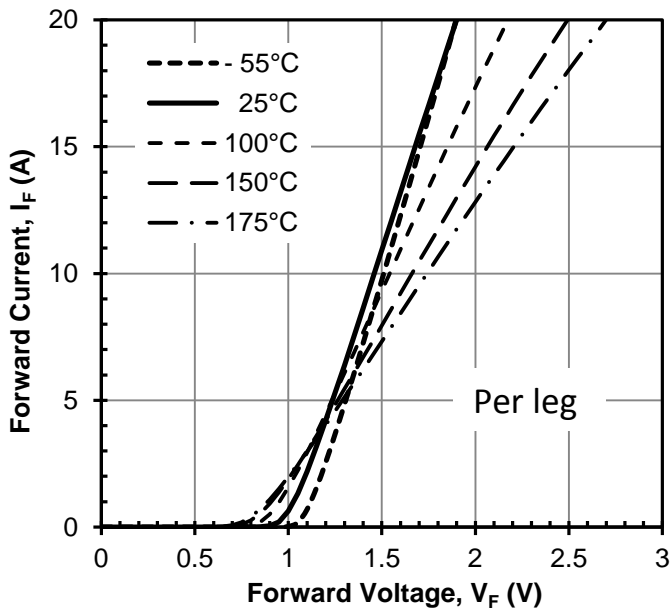


Figure 1 Typical forward characteristics per leg

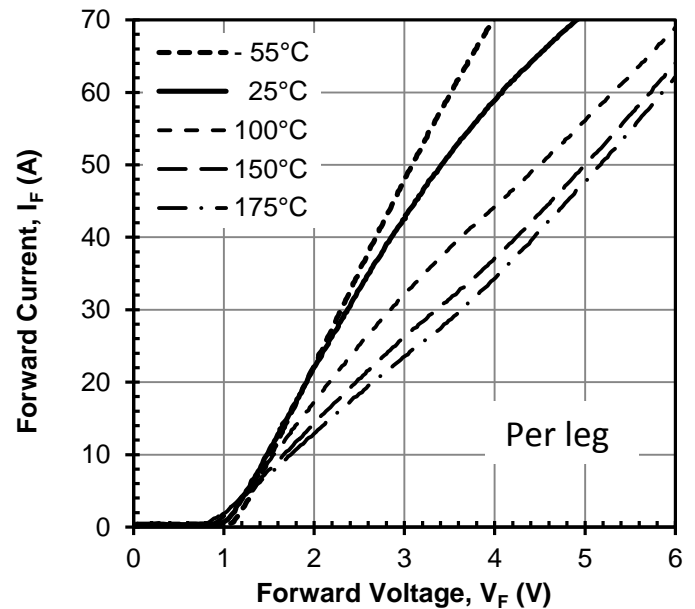


Figure 2 Typical forward characteristics in surge current per leg

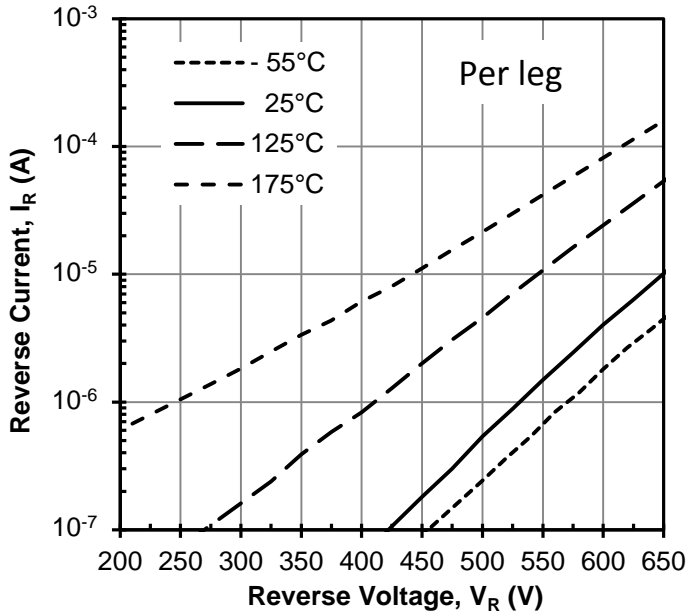


Figure 3 Typical reverse characteristics per leg

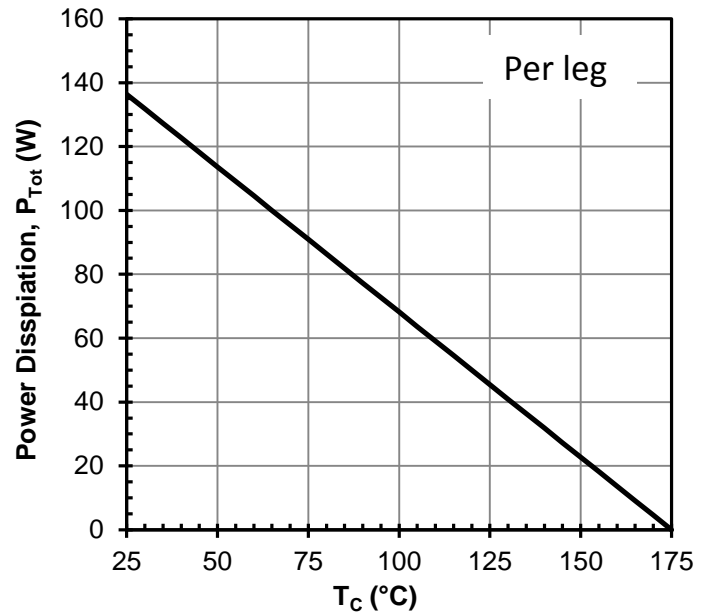


Figure 4 Power dissipation per leg

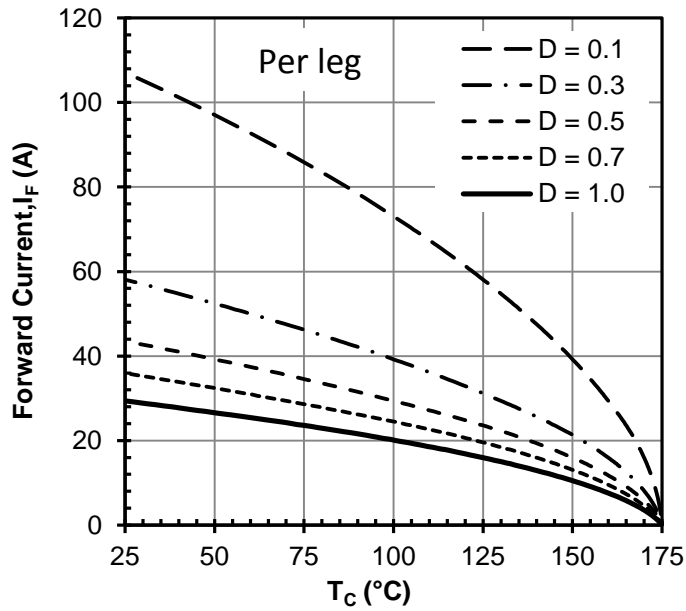


Figure 5 Diode forward current per leg

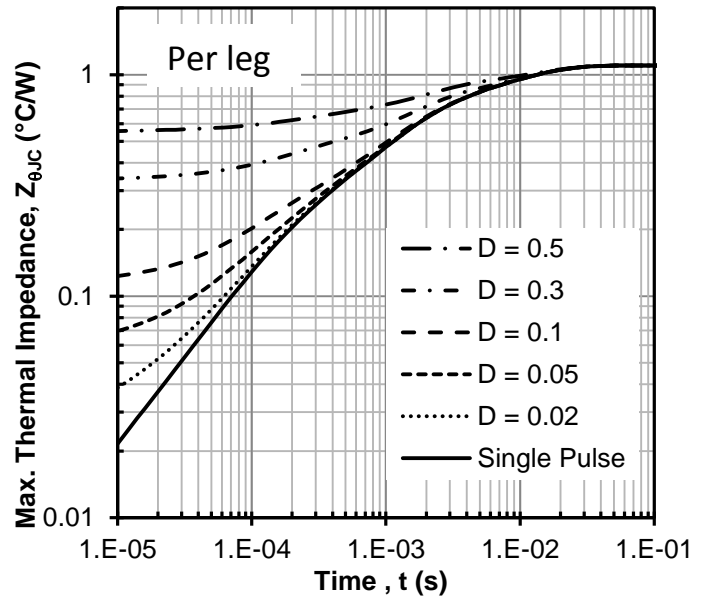


Figure 6 Maximum transient thermal impedance per leg

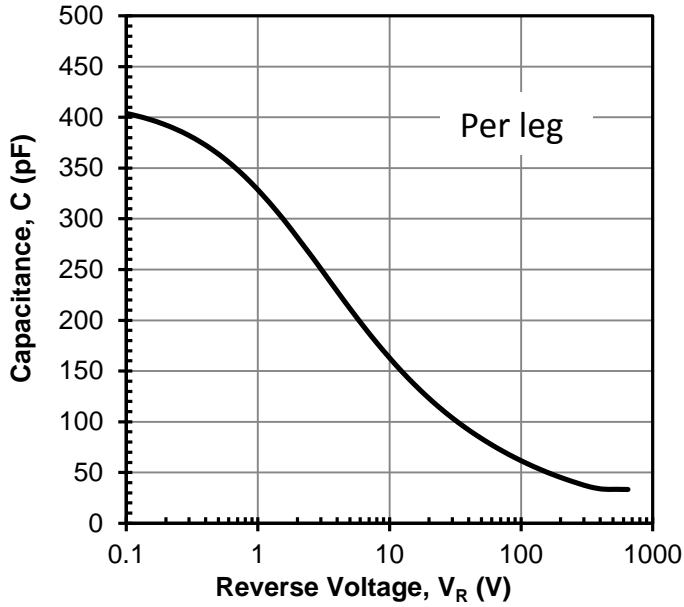


Figure 7 Capacitance per leg vs. reverse voltage at 1MHz

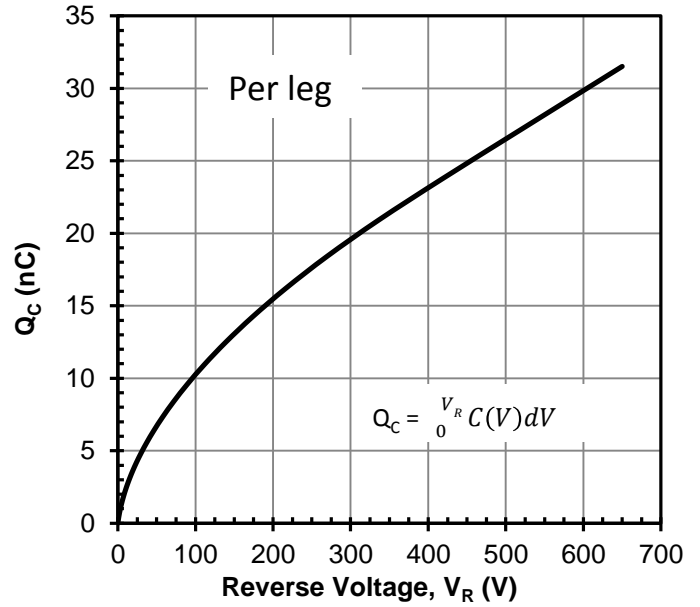


Figure 8 Typical capacitive charge per leg vs. reverse voltage

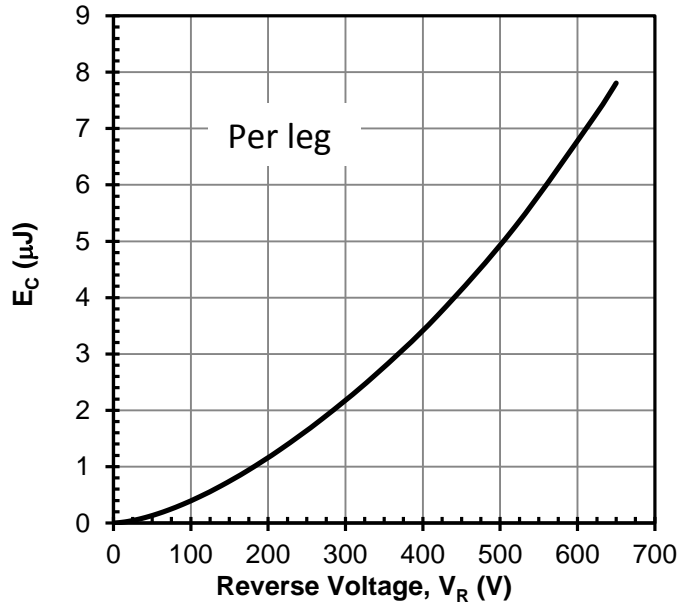


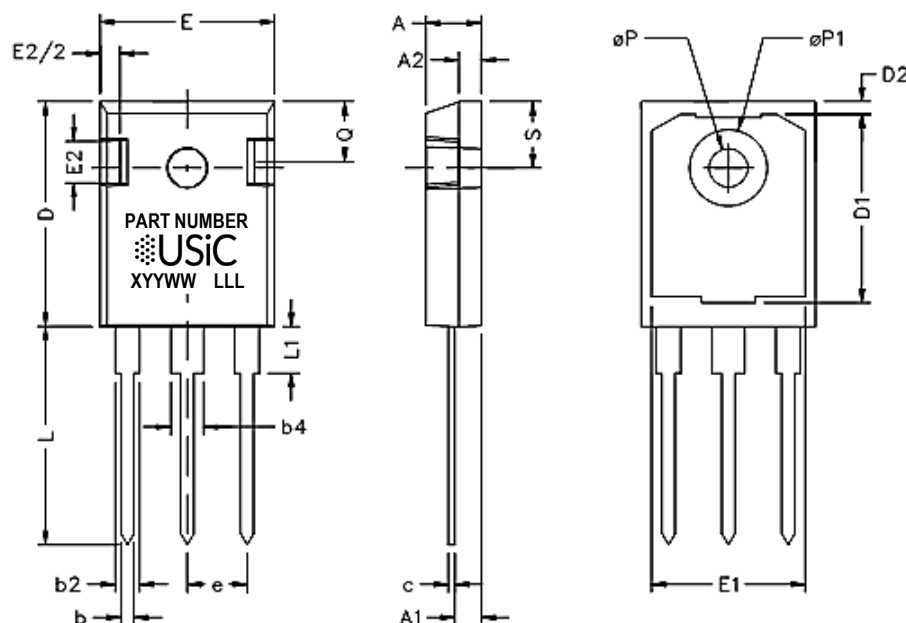
Figure 9 Typical capacitance stored energy per leg vs. reverse voltage

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PACKAGE OUTLINE


SYM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	0.185	0.209	4.699	5.309
A1	0.087	0.102	2.21	2.61
A2	0.059	0.098	1.499	2.489
b	0.039	0.055	0.991	1.397
b2	0.065	0.094	1.651	2.388
b4	0.102	0.135	2.591	3.429
c	0.015	0.035	0.381	0.889
D	0.819	0.845	20.803	21.463
D1	0.515	-	13.081	-
D2	0.02	0.053	0.508	1.346
E	0.61	0.64	15.494	16.256
e	0.214 BSC		5.44 BSC	
E1	0.53	-	13.462	-
E2	0.135	0.157	3.429	3.988
L	0.78	0.8	19.812	20.32
L1	-	0.177	-	4.496
$\varnothing P$	0.14	0.144	3.556	3.658
$\varnothing P1$	0.278	0.291	7.061	7.391
Q	0.212	0.244	5.385	6.198
S	0.243 BSC		6.17 BSC	

PART MARKING**PART NUMBER**
XYYWW LLL

PART NUMBER = REFER TO
DS_PN DECODER FOR DETAILS

X = ASSEMBLY SITE

YY = YEAR

WW = WORK WEEK

LLL = LOT ID

PACKING TYPE**ANTI-STATIC TUBE****QUANTITY /TUBE : 30 UNITS****DISCLAIMER**

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